

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	N/A	Silicon Carbide (SiC)	409-21-2	0.06175	100.0	0.28
			<b>Subtotal</b>	<b>0.06175</b>	<b>100</b>	<b>0.28</b>
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.00397	2.0	0.018
	Lead alloy	Silver (Ag)	7440-22-4	0.00496	2.5	0.0225
	Lead alloy	Lead (Pb)	7439-92-1	0.18954	95.5	0.8595
			<b>Subtotal</b>	<b>0.19847</b>	<b>100</b>	<b>0.9</b>
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.11252	100.0	0.51026
			<b>Subtotal</b>	<b>0.11252</b>	<b>100</b>	<b>0.51026</b>
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.01152	0.03	0.05226
	Copper alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.01152	0.03	0.05226
	Copper alloy	Iron (Fe)	7439-89-6	0.03841	0.1	0.1742
	Copper alloy	Copper (Cu)	7440-50-8	38.3534	99.84	173.92128
			<b>Subtotal</b>	<b>38.41485</b>	<b>100</b>	<b>174.2</b>
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.22551	3.8	10.09204
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	3.51397	6.0	15.9348
	Filler	Silica fused	60676-86-0	52.70952	90.0	239.022
	Carbon Black	Carbon black	1333-86-4	0.11713	0.2	0.53116
			<b>Subtotal</b>	<b>58.56613</b>	<b>100</b>	<b>265.58</b>
Post-plating	Pure metal	Tin (Sn)	7440-31-5	2.64626	100.0	12
			<b>Subtotal</b>	<b>2.64626</b>	<b>100</b>	<b>12</b>
			<b>Total</b>	<b>99.99998</b>	<b>100</b>	<b>453.47026</b>

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